

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2.1x0.6mm RIGHT ANGLE SURFACE LED **LAMP**

Part Number: APA2106SECK Super Bright Orange

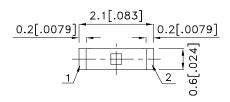
Features

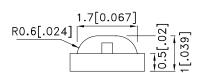
- 2.1mmX0.6mm right angle SMT LED, 1.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

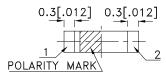
The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

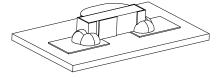
Package Dimensions











- 1. All dimensions are in millimeters (inches).
- 2.Tolerance is ±0.1(0.004") unless otherwise noted.
- 3.The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 4. The device has a single mounting surface. The device must be mounted according to the specifications

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
APA2106SECK	Super Bright Orange (AlGaInP)	Water Clear	110	250	120°
		Water Clear	*80	*180	

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	I=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I=20mA
IR	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

- Navelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Navelength value is traceable to the CIE127-2007 compliant national standards.

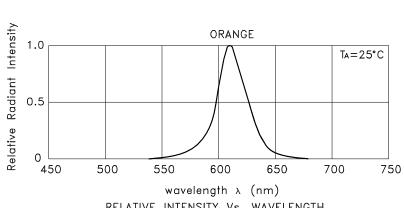
Absolute Maximum Ratings at TA=25°C

Units		
mW		
mA		
mA		
V		
-40°C To +85°C		
-40°C To +85°C		
_		

Note:

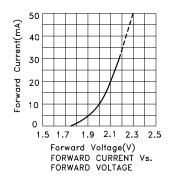
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

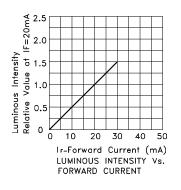
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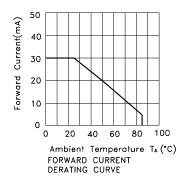


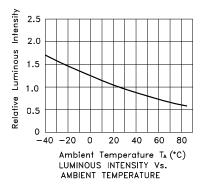
RELATIVE INTENSITY Vs. WAVELENGTH

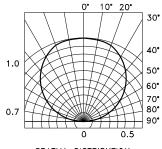
Super Bright Orange APA2106SECK











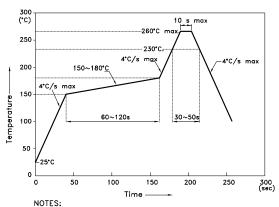
SPATIAL DISTRIBUTION

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APA2106SECK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



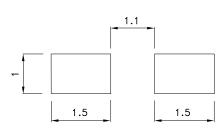
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

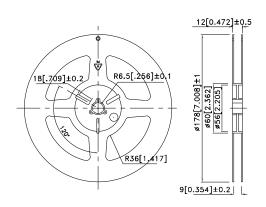
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



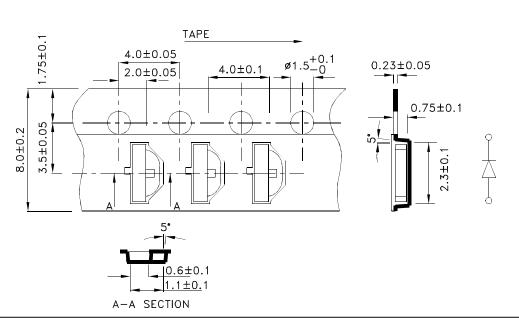
Tape Dimensions (Units : mm)

Reel Dimension

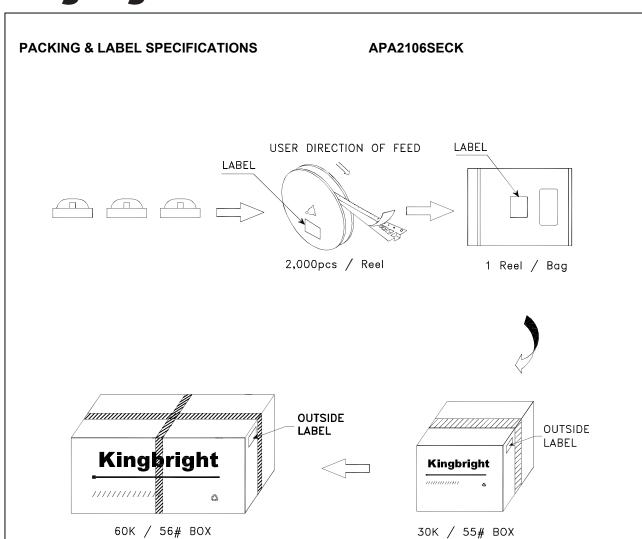


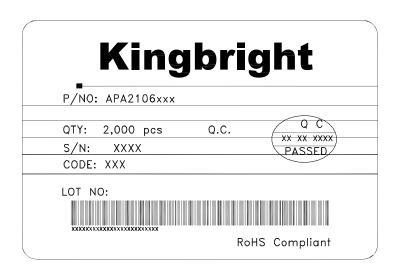
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